

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2023/0230978 A1 Huang et al.

Jul. 20, 2023 (43) **Pub. Date:**

(54) SENSING DEVICE

- (71) Applicant: AUO Corporation, Hsinchu (TW)
- (72) Inventors: **Te-Chun Huang**, Hsinchu (TW); Pei-Ming Chen, Hsinchu (TW)
- (73) Assignee: AUO Corporation, Hsinchu (TW)
- (21) Appl. No.: 17/882,622
- (22) Filed: Aug. 8, 2022

Related U.S. Application Data

- (60) Provisional application No. 63/300,734, filed on Jan. 19, 2022.
- (30)Foreign Application Priority Data

Jun. 9, 2022 (TW) 111121419

Publication Classification

(51) Int. Cl. H01L 27/12 (2006.01)H01L 27/32 (2006.01)H01L 29/868 (2006.01)

U.S. Cl. CPC H01L 27/124 (2013.01); H01L 27/3272 (2013.01); H01L 29/868 (2013.01)

(57)**ABSTRACT**

A sensing device has a sensing area, a pad area, and a peripheral area, and the pad area is located between the sensing area and the peripheral area, including: a sensing element, a pad, and a metal strip. The sensing element is located in the sensing area. The pad is located in the pad area and electrically connected to the sensing element. The metal strip is located in the peripheral area, and an extending direction of the metal strip is parallel to an extending direction of the pad.

